



GE Energy

Functional Testing Specification

*Parts & Repair Services
Louisville, KY*

LOU-GENEVA-IS215VAMB

Test Procedure for IS200VSPA/IS215VAMB card tested on the GENEVA Test System

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DATE 4/7/2014	DATE	DATE	DATE 6/11/2014

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**Functional test procedure for IS215VAMBH1A Acoustic Monitoring Card Assembly tested on the
GENRAD® GENEVA system**

1. SCOPE

1.1 This is a functional testing procedure for IS200VSPA/IS215VAMB boards.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check the board's electronic folder for more information.

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires broken or cracked

4.2.1.2 Terminal strips / connectors broken or cracked

4.2.1.3 Loose wires

4.2.1.4 Components visually damaged

4.2.1.5 Capacitors leaking

4.2.1.6 Solder joints damaged or cold

4.2.1.7 Circuit board burned or de-laminated

4.2.1.8 Printed wire runs burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1	H188912	GENRAD Geneva Test System
1	H188969	VSPA/VAMB Test Fixture

6. Testing Process

6.1 Setup

6.1.1 Install fixture H188969 onto Geneva test System.

6.1.2 Install UUT into test fixture.

6.2 Testing Procedure

6.2.1 Load appropriate test program and follow instructions on screen.

6.3 *TEST COMPLETE *****

7. Notes

7.1 Changes to the electronic test file are located in the following directory on the local hard drive; C:\GenevaInfo\Geneva\Geneva Test Fixture Notes. These changes have been backed up on CD.

7.2 ECN summary

7.2.1 IS200VSPAH1AAA TO IS200VSPAH1AAA-W06: CHANGE U500 FROM 44S770283-001B TO 44S770283-001D

7.2.2 IS200VSPAH1ABA TO IS200VSPAH1ABA-W06: CHANGE U500 FROM 44S770283-001C TO 44S770283-001E

7.2.3 IS200VSPAH1ABB is Scrap, no possible upgrade due to construction defects, too thick for rack.

7.2.4 IS200VSPAH1ABC TO IS200VSPAH1ACC: CHANGE U500 FROM 44S770283-001C TO 44S770283-001E

8. Attachments

8.1 Picture of the Geneva Test System

